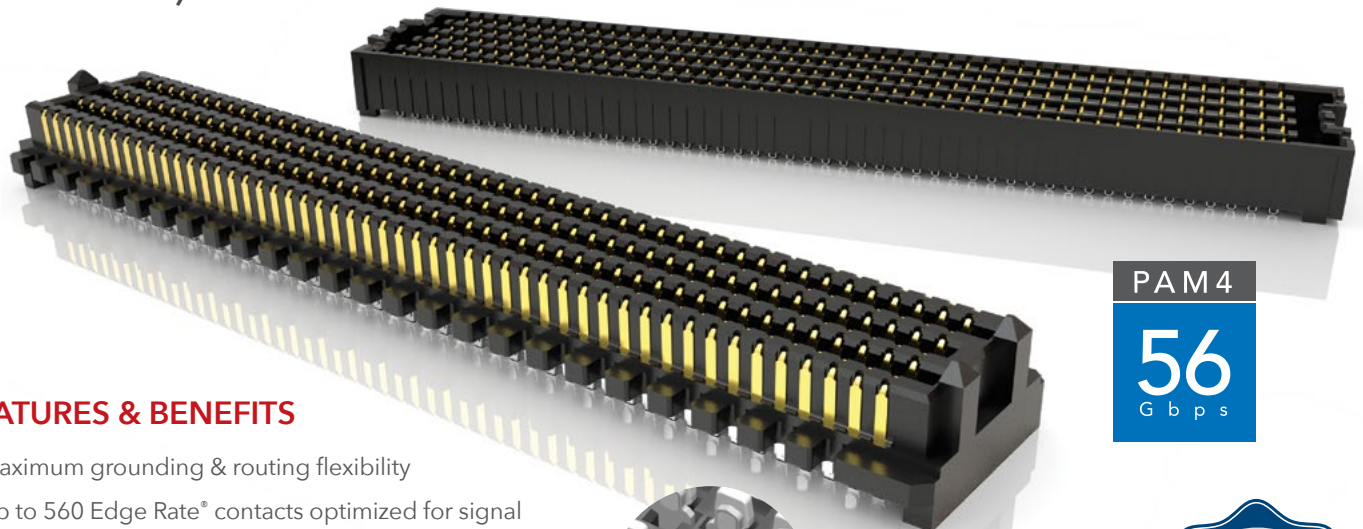




HIGH-DENSITY OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH



PAM 4
56
G b p s

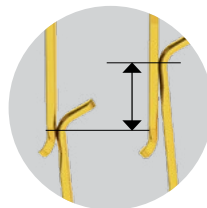
FEATURES & BENEFITS

- Maximum grounding & routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance.
- 7 mm to 40 mm stack heights
- Variety of designs and options: Right-Angle, Guide Posts, 85 Ω Elevated Risers, 85 Ω Tuned, Press-Fit and Press-Fit Right-Angle, Guide Post Field Termination Kits
- Cable mates (SEAC Series) and Jack Screw Standoffs (JSO Series) also available
- Standards: VITA 47, VITA 57.1 FMC, VITA 57.4 FMC+, VITA 74 VNX, PISMO™ 2
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel & InfiniBand™
- Severe Environment Testing qualified (SEAM/SEAF); aligns with MIL-DTL-55302. Visit samtec.com/set



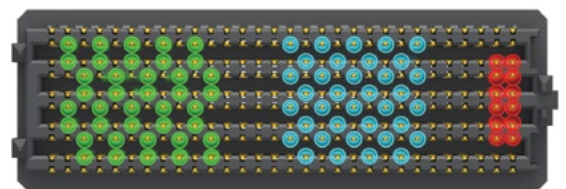
Solder Charges

EDGE RATE
CONTACT



(1.12 mm) .044"
Nominal Wipe

MAXIMUM GROUNDING & ROUTING FLEXIBILITY



Differential Pair Single-Ended Power

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM/SEAF	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC	Yes
SEAM-RA/SEAF-RA	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (10 pins powered)	260 VAC	Yes
SEAM-GP	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC	Yes
SEAMP/SEAFP	Natural High Temp Nylon	Copper Alloy (SEAMP) BeCu Alloy (SEAFP)	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (6 pins powered)	225 VAC	Not Available
SEAR	Black LCP	Hard Gold Plated	Au over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	Contact Samtec	240 VAC	Not Available
SEAMI	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	Not Available	Not Available	Yes

Note: Some lengths, styles and options are non-standard, non-returnable

(1.27 mm) .050" PITCH • PRESS-FIT & 85 Ω OPEN-PIN-FIELD ARRAYS

SERIES	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	OPTION	PACKAGING
SEAMP Terminal	-10, -20, -30, -40, -50	-02.0 (SEAMP only)	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on tail	-04, -06, -08, -10	-GP Guide Post (SEAMP only)	-TR = Tape & Reel
SEAFP Socket		-05.0 (SEAFP only)	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on tail	SEAFP: -04 & -06 Rows only		-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

SEAMP
Board Mates:
SEAF,
SEAF-RA-GP,
SEAFP

NO. OF ROWS	A
-04	(7.06) .278
-06	(9.60) .378
-08	(12.14) .478
-10	(14.68) .578

SEAFP
Board Mates:
SEAM,
SEAM-RA,
SEAMP

NO. OF ROWS	A
-04	(5.61) .221
-06	(8.15) .321

View complete specifications at: samtec.com?SEAMP & samtec.com?SEAFP. Visit samtec.com?SEAFP-RA for right-angle socket.

SERIES	POSITIONS PER ROW	LEAD STYLE	NO. OF ROWS	085
SEAR 85 Ω Tuned Riser	-40, -50	-10.0 = 20 mm Mated Height -20.0 = 30 mm Mated Height -30.0 = 40 mm Mated Height	-06, -08, -10	

SEAR
Board Mates:
SEAFC

POSITIONS PER ROW	A
-40	(71.42) 2.812
-50	(84.12) 3.312

NO. OF ROWS	B
-06	(11.43) .450
-08	(13.97) .550
-10	(16.51) .650

SERIES	POSITIONS PER ROW	11.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	K	"X"R
SEAMI 85 Ω Tuned Terminal	-40 -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-08 -10	-1 = Tin/Lead Alloy SolderCharge			-TR = Tape & Reel
SEAMI			-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail		-2 = Lead-Free Solder Charge			-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

SEAMI
Board Mates:
SEAF

Note: Some lengths, styles and options are non-standard, non-returnable

NO. OF ROWS	A
-08	(13.41) .528
-10	(15.95) .628

View complete specifications at: samtec.com?SEAR & samtec.com?SEAMI.